

Press Release

Viscom SI Release 7.46 – more performance for Viscom 3-D SPI, AOI and AXI

Hanover, June 2013 – **With the Software Release SI 7.46, the developers at Viscom have integrated many new functionalities that further increase the performance capability of its inspection systems. This reaches from cycle time reduction for typical component types through improvements in the global use of inspection libraries, up to innovations in the areas of 3-D SPI and X-ray inspection. All innovations involve the Viscom software SI.**

The SI Release 7.46 provides customers with innovations that further boost the performance and convenience of both optical and X-ray inspection. Additionally, the new software version features numerous other improvements that relieve the operator and increase system performance.

For example, AOI inspection times can be further reduced with the 8M technology. This has been accomplished through improved optimization of the travel paths. This way, the same reliable inspection can be attained with fewer axis positions.

An additional highlight is the integration of the Library Manager. By using this software tool, new inspection patterns can be assigned even more quickly and easily. Therefore, the use of local and global inspection libraries is even more convenient. The new functionality can be used in parallel with the tried and tested library toolbox.

Another software advancement concerns the AOI Desktop system S2088-II and was initiated by a customer request. It enables the detailed appraisal of recognized defects in parallel with defect verification. In the review process, live images of the defects can be displayed on the HARAN verification station. The camera head moves directly to the defect position with a simple keypress. Thus, a live capture of the defect image can be viewed

under different camera perspectives — orthogonal and angled — and in color.

Release 7.46 also brings further interesting developments in 3-D solder paste inspection. This inspection has proven itself in practice and due to Quality Uplink, enables convenient process optimization. With the new Release, the SPI Closed Loop (Downlink) has been completely integrated. With it, it is possible to return currently measured displacement values of the SPI inspection to the paste printer as offset correction values. Thus, an automatic correction of the print stencil can be carried out if the print image is displaced during production. Furthermore, there is an option to initiate automatic cleaning of the paste printer. EKRA, DEK and Speedline (MPM) interfaces already have been successfully implemented in field test; other interfaces can be integrated on request or already are in development.

Image caption: 3-D display of a solder paste defect with the Viscom SPI 3-D Viewer.